

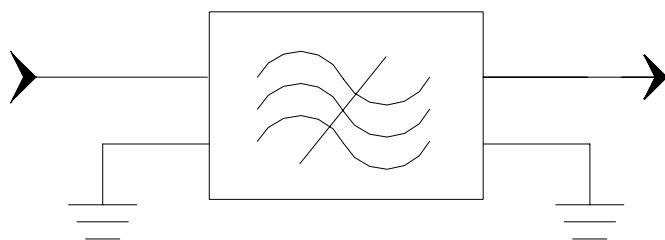
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	69.95	70	70.05
Insertion Loss	dB		21	22.5
3dB Bandwidth	MHz	7.9	8	8.1
25dB Bandwidth	MHz		8.7	8.8
35dB Bandwidth	MHz		8.87	9.2
40dB Bandwidth	MHz		8.9	10
50dB Bandwidth	MHz		9	12
Passband Variation	dB		0.5	1
Group Delay Variation($f_0 \pm 3.6\text{MHz}$)	nsec		100	150
Absolute Delay	usec		2.94	3
Ultimate Rejection($f_0 \pm 6\text{MHz}$)	dB	55	60	
Material temperature coefficient	KHz/°C		-6.58	
Ambient Temperature	°C		25	
Package Size		DIP3512 (35.2x12.7x5.2mm ³)		

Notes:


1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

Matching Configuration

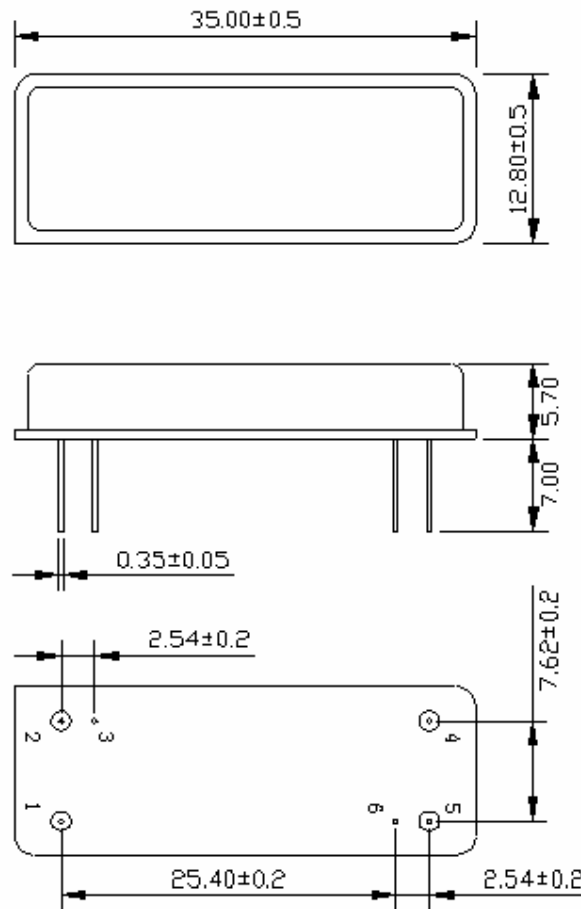



Source/Load Impedance=50 ohm

Notes - Component values may change depending
on board layout.

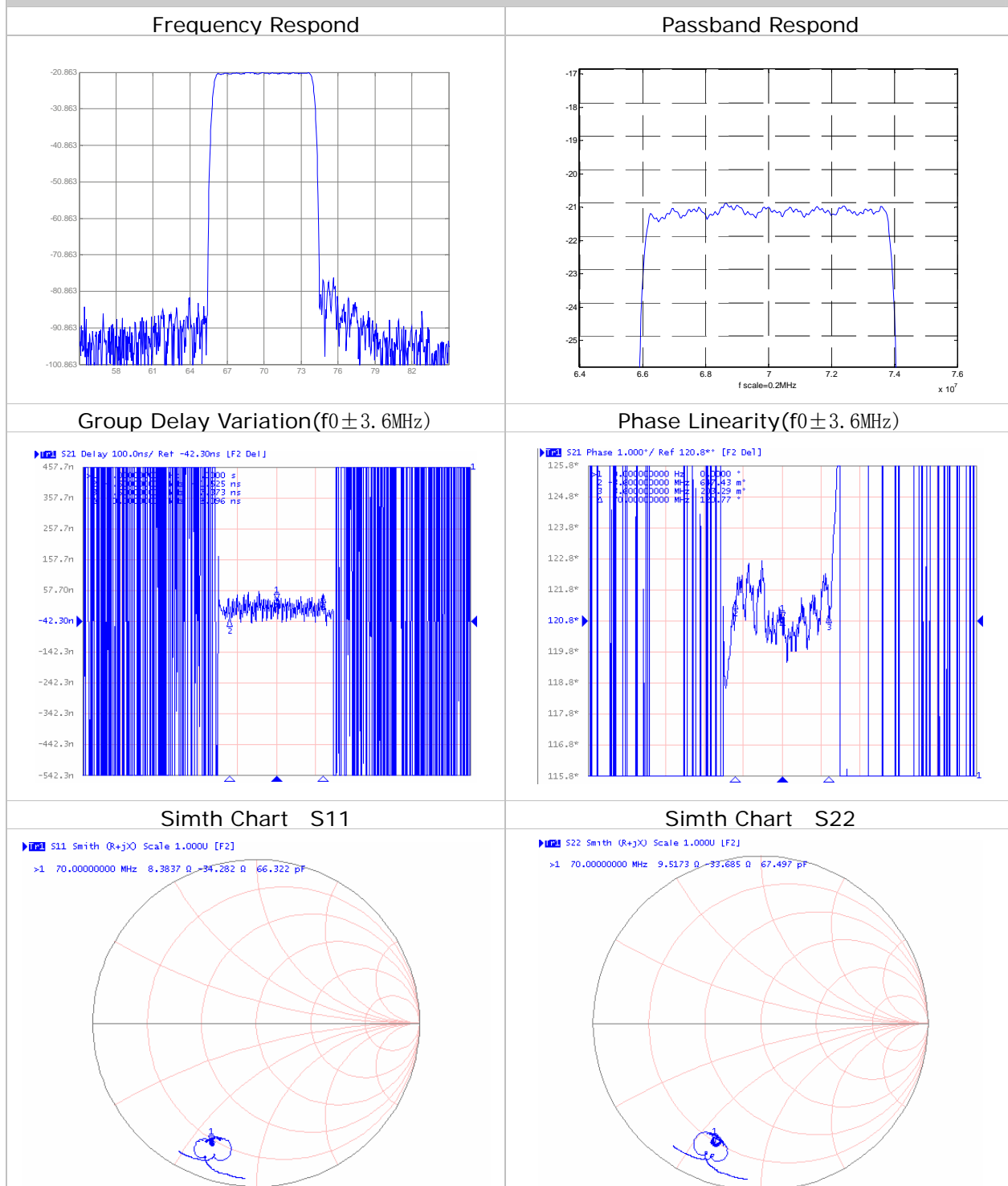
	SIPAT Co., Ltd. (CETC No. 26 Research Institute) Nanping Huayuan Road No. 14 Chongqing, China, 400060	Part Number	LBN07098	
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Package Dimension



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Typical Performance



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